

MC33816 Diagnostics

1 Introduction

This application note explains how to use MC33816 diagnostics in a typical four cylinder internal combustion engine (ICE) application. The field of powertrain is just one example where diagnostics are required at very high speed. The 33816 diagnostics manage this through four independent microcores.

This application note seeks to address different fault cases and describes how to program the microcode to detect them during idle and actuation mode.

NXP analog ICs are manufactured using the SMARTMOS process, a combinational BiCMOS manufacturing flow that integrates precision analog, power functions, and dense CMOS logic together on a single cost-effective die.

2 Overview

The 33816 is a 12 channel gate driver IC for automotive engine control applications. The IC consists of five external MOSFET high-side pre-drivers and seven external MOSFET low side pre-drivers. The 33816 provides a flexible solution for the MOSFET's gate drive with a versatile control and optimized latency time. Gate drive, diagnosis, and protection are managed through four independent microcores, two Code RAM, and two Data RAM banks.

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3 Application Schematic

The MC33816 typical application controls two injection banks, one DC-DC and a Pump Bank.

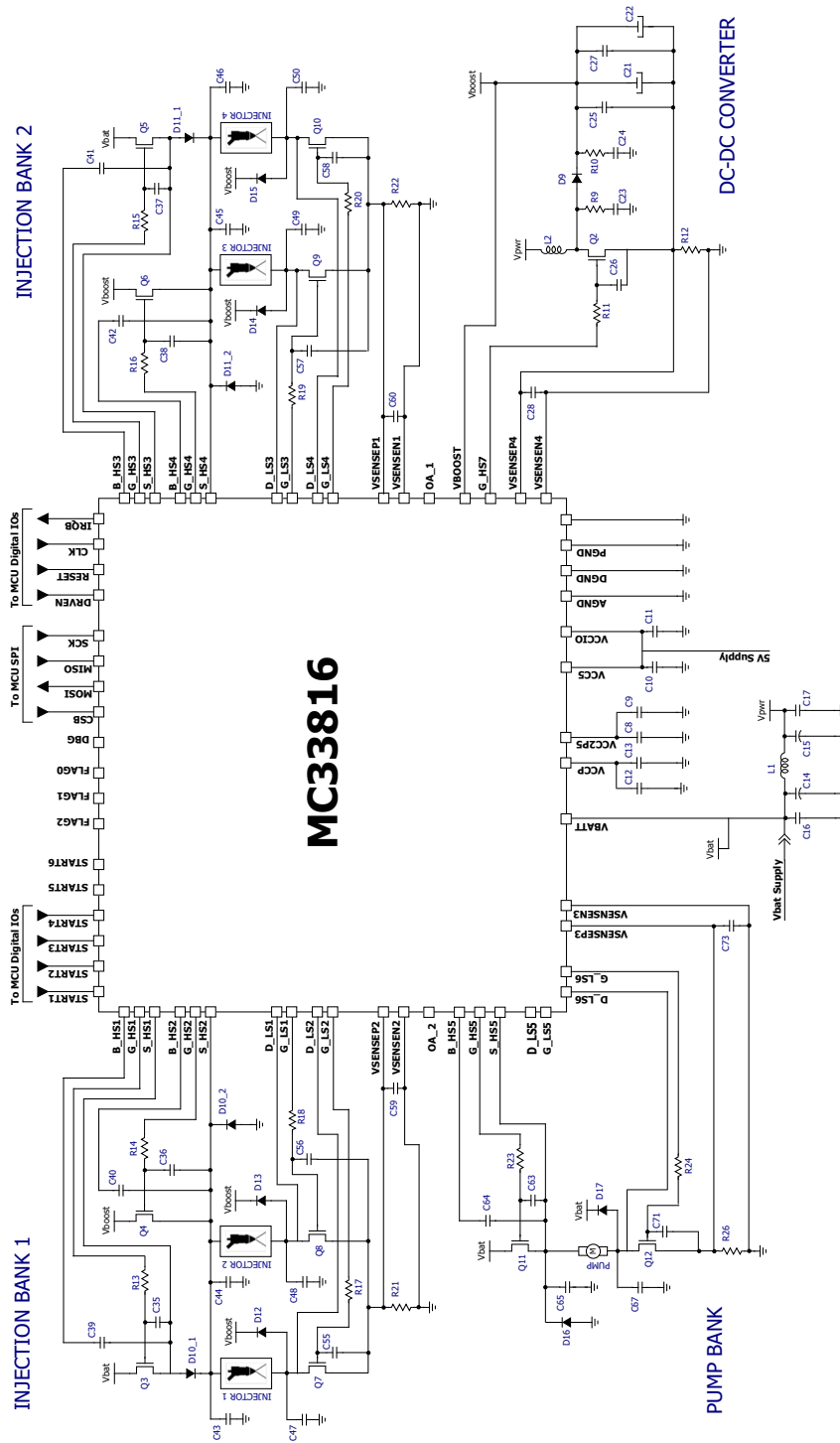


Figure 1. Typical Four Injector Two Bank Application Schematic

4 Application Instructions

This topology can be used on the evaluation board [KIT33816FRDMEVM](#). Register settings and microcode downloads can be achieved by using the KL25Z embedded on the KIT33816FRDMEVM.

Each bank is individually managed by one microcore of the digital channel 1 as described next:

- The bank # 1 is managed by the digital microcore Uc0Ch1 with diagnostics
- The bank # 2 is managed by the digital microcore Uc1Ch1 without diagnostics

The two microcores of the second channel (Channel 2) drive the DC-DC and the fuel pump as described next:

- The VFM (Variable Frequency Modulation) is managed by the digital microcore Uc0Ch2
- The fuel pump is managed by the digital microcore Uc1Ch2.

This application note only focuses on BANK1 diagnostics managed by the digital microcore Uc0Ch1. Refer to [AN4849](#) for register settings and microcode related to injection or DC-DC, unless specified in this document.

The following is the start-up sequence:

- Apply a battery voltage between 9.0 V and 16 V
- Download the registers Channel Configuration, Main Configuration, IO Configuration, and Diagnostic Configuration
- Download the dedicated microcode in the Logic Channel 1 and Logic Channel 2 Data RAM
- Set '1' in the pre-flash enable bit and en dual seq bit in the Flash_enable register of channel 1 (0x100) and channel 2 (0x120)

The register configurations and the microcodes are detailed in the following chapters.

Table 1. Example of Injection Current Profile Key Parameters

Parameter Name	Description	Value
I_{BOOST}	Current threshold in Boost Phase	16.09 A
I_{PEAK}	Current threshold in Peak Phase (Depends on injectors type)	14.89 A
I_{HOLD}	Current threshold in Hold Phase	8.89 A
t_{PEAK_OFF}	Fixed time for high-side switch off in Peak Phase	10 μ s
t_{PEAK_TOT}	Fixed time for end of Peak Phase	500 μ s
t_{BYPASS}	Fixed time for Bypass Phase	20 μ s
t_{HOLD_OFF}	Fixed time for high-side switch off in Hold Phase	10 μ s
t_{HOLD_TOT}	Fixed time for end of Hold Phase (timeout)	10 ms
$t_{INJMAXBOOST}$	Maximum time allowed to reach I_{BOOST} (Depends on injectors type)	500 μ s

Application Instructions

Diagnostics interrupts description:

Diagnostics interrupts are handled in two different subroutines: automatic interrupt and software interrupt.

Status_reg_uc0 register (0x105) is used to inform MCU on error detected, and then control register is used to unlock the Bank. In all cases, the IRQB pin is set low to inform the MCU about the error detected in MC33816.

Software Interrupts can be filtered by their req id (stored in Uc0_irq_status Registers 0x10F):

Pre-Diagnostics checks (req id = 1): interrupt occurs if the high-side V_{BOOST}/V_{BAT} , V_{DS} or V_{SRC} are low or V_{DS} low-side is low. If an error occurs, the Status_reg_uc0 register (0x105) bit 7 sets high, Bank1 sets OFF, and MCU needs to write a 1 to the control register (0x101) bit 7 to unlock the Bank1.

Boost Error (Req id = 1): If I_{BOOST} is not reached before $t_{INJMAXBOOST} = 500 \mu s$, this number has to be set according to the injector characteristics.

If an error occurs, Status_reg_uc0 register (0x105) bit 5 sets high, Bank1 sets OFF, and MCU needs to write a 1 to the Ctrl_reg_uc0 register (0x101) bit 5 to unlock the Bank1.

Hold Error (Req id = 2): If Start signal is still high after t_{HOLD_OFF} .

If an error occurs, the Status_reg_uc0 register (0x105) bit 4 sets high, Bank1 sets OFF, and MCU needs to write a 1 to the Ctrl_reg_uc0 register (0x101) bit 4 to unlock the Bank1.

An automatic Interrupt occurs during actuation, if comparators feedback is different than the error table (see [Diagnostics Configuration Registers](#)).

If an error occurs, the Status_reg_uc0 register (0x105) bit 6 sets high, Bank1 sets OFF, and MCU needs to write a 1 to the Ctrl_reg_uc0 register (0x101) bit 6 to unlock the Bank1.

Table 2. Status_reg_uc0 Registers (0x105) Configuration

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	status_register															
Value	X	X	X	X	X	X	X	X	SW Interrupt Status	Auto Interrupt Status	Boost Error Status	Hold Error Status	X	X	X	X

Reading this register indicates the type of fault.

Table 3. Ctrl_reg_uc0 Registers (0x101) Configuration

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	control_register_shared								control_register							
Value	X	X	X	X	X	X	X	X	SW Interrupt Unlock	Auto Interrupt Unlock	Boost Error Unlock	Hold Error Unlock	X	X	X	X

Depending on the status register information, one of the bits must be set to 1 to unlock the BANK.

5 Diagnostic Descriptions

The MC33816 gives the possibility to check faults using two different methods:

- Automatic diagnostics (Actuation phase):
 - Boost Phase (HSBoost ON): automatic diagnostics are used during actuation phase; it performs a coherency check between an output and the related V_{DS} feedback (for all the outputs) and V_{SRC} feedback (for the high-side outputs only).
 - Peak and Hold phase (HSBat ON): automatic diagnostics are used during actuation phase; it performs a coherency check between an output and the related V_{DS} feedback (for all the outputs) and V_{SRC} feedback (for the high-side outputs only).
- Idle Diagnostics (Pre-actuation): Internal voltage biasing V_{BIAS} should be applied to the load to enable diagnostics in this phase.

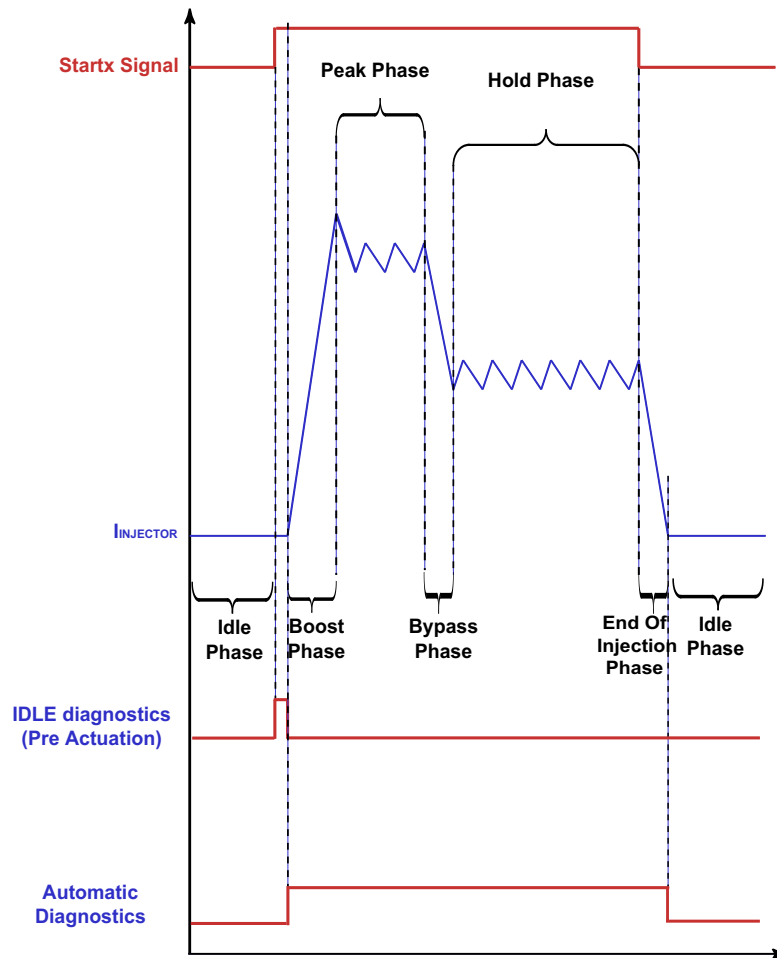


Figure 2. Typical Peak and Hold Current Profile with Diagnostics

Several fault cases could occur in the application, this chapter describes most of them, and explains how the MC33816 is able to detect them.

Diagnostic Descriptions

5.1 Idle Diagnostics (Pre-actuation)

As described in [Figure 2](#), idle diagnostics start after a rising edge on the start 1 or start 2 (Bank 1). A voltage biasing V_{BIAS} should be applied to the load, to enable electrical diagnosis while the external load is not actuating the power stage.

This V_{BIAS} voltage is generated by:

- the activation of the SRC_{PUX} pull-up voltage source connected to each of the S_HSx pins. Each pull-up voltage source is supplied from $VCC5$
- the activation of each SRC_{PDX} pull-down current source connected to each of the D_LSx pins. Each pull-down voltage source is referenced to ground

When the battery voltage V_{BATT} is in the nominal range or greater, the external load is biased at a minimum voltage of typically 3.8 V. In a low battery voltage condition ($V_{BATT} < 8.0$ V), the load is biased at half the V_{BATT} voltage, to guarantee symmetrical voltage margins to high-side and low-side V_{DS} comparators.

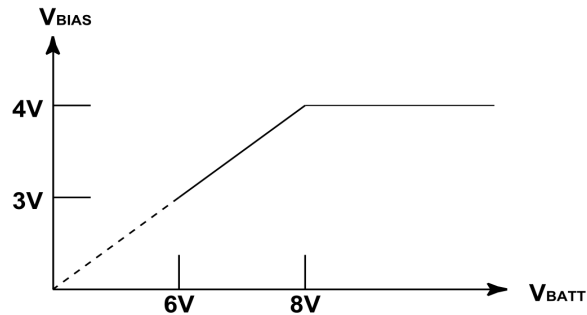


Figure 3. Biasing Voltage vs. V_{BATT}

The bias generators can be kept ON even during actuation, to control the voltage on the source, even if the MOSFET is OFF. This does not impact the application, because of their low strength. If at least one MOSFET is turned ON, it fixes the voltage on the load and does not affect the bias.

These pre-actuation diagnostics are used to ensure the injectors can be turned ON safely. If an error occurs in any of the following cases, the MC33816 keeps Bank 1 OFF until the MCU writes a 1 through the SPI to the `Ctrl_reg_uc0` register (0x101) bit 7.

5.1.1 Normal Behavior

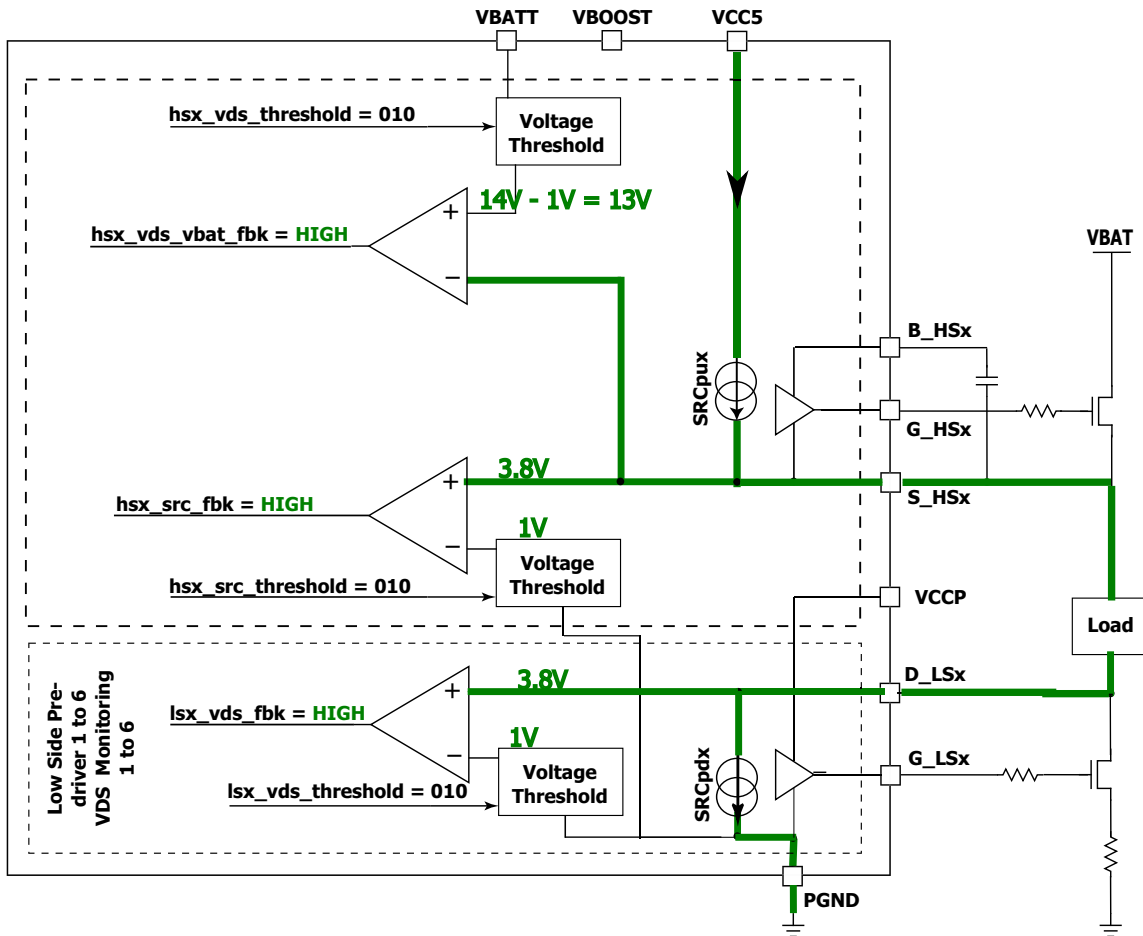


Figure 4. Idle Normal Mode

During normal operation, a current limited pull-up voltage source (SRC_{PUX}) generates a voltage on S_{HSx} (min. 3.8 V). Its current goes to the load and to a pull-down current source on D_{LSx}, generating a 3.8 V min. voltage. Drain source voltage on the high-side is not monitored directly, and since there is no pin for the drain, monitoring is directly done from V_{BAT} or V_{BOOST}, and only HS2 and HS4 can use V_{BOOST} as a reference. Voltage thresholds are selected to be lower than the voltage generated.

Table 4. Normal Mode Truth Table

Error Case	LSx_vds_fbk	HSx_src_fbk	Hsx_vds_Vbat_fbk	S_HSx voltage V _{BAT}	D_LS_x voltage
Normal mode	1	1	1	3.8	3.8

5.1.2 High-side Source or Low-side Drain Shorted to GND

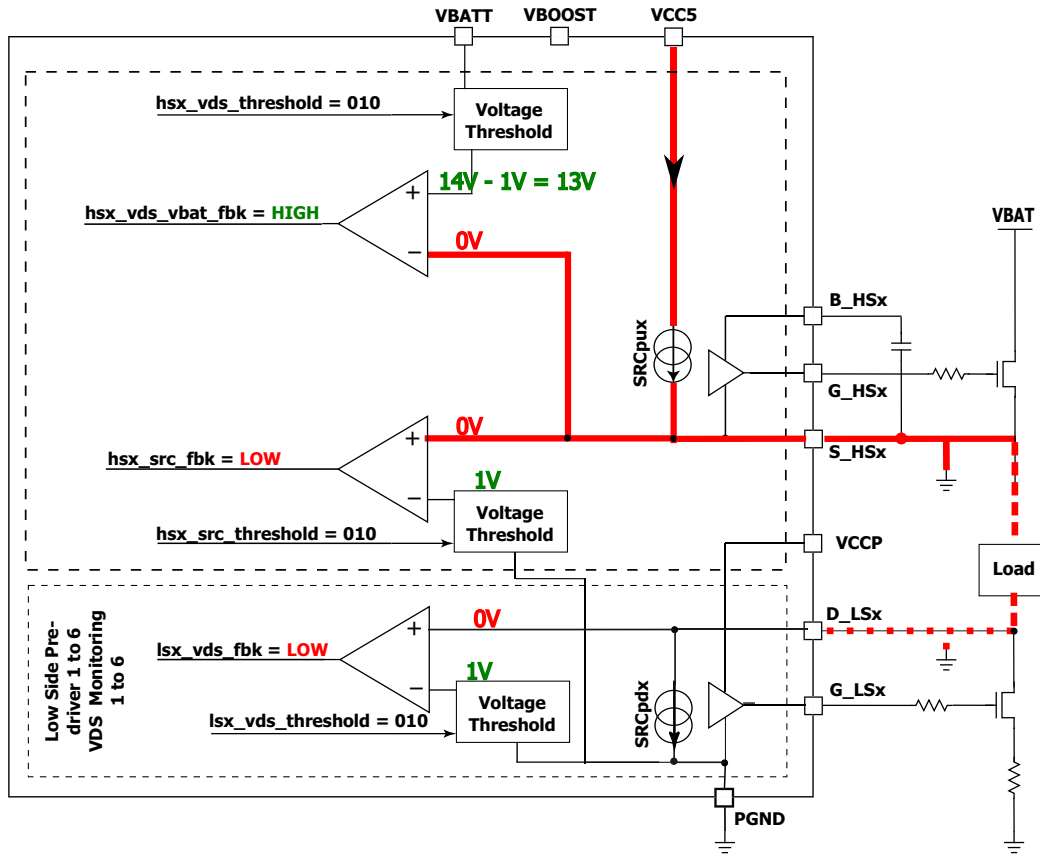


Figure 5. High-side Source or Low-side Drain Shorted

In cases where the High Source (S_HSx) shorts to GND or the Low-side Drain (D_LSx) shorts to GND, the current limited voltage source pulls to ground, and the voltage on S_HSx and D_LSx is 0 V. A diagnostic error is detected, and since the high-side V_{src} and low-side V_{ds} feedback are low, the bank does not turn ON.

Table 5. S_HSx or D_LSx Shorted to GND Truth Table

Error Case	LSx_vds_fbk	HSx_src_fbk	Hsx_vds_Vbat_fbk	S_HSx voltage V _{BAT}	D_LS_x voltage
Normal mode	1	1	1	3.8	3.8
D_LS GND short	0	0	1	0	0

5.1.5 Open Load

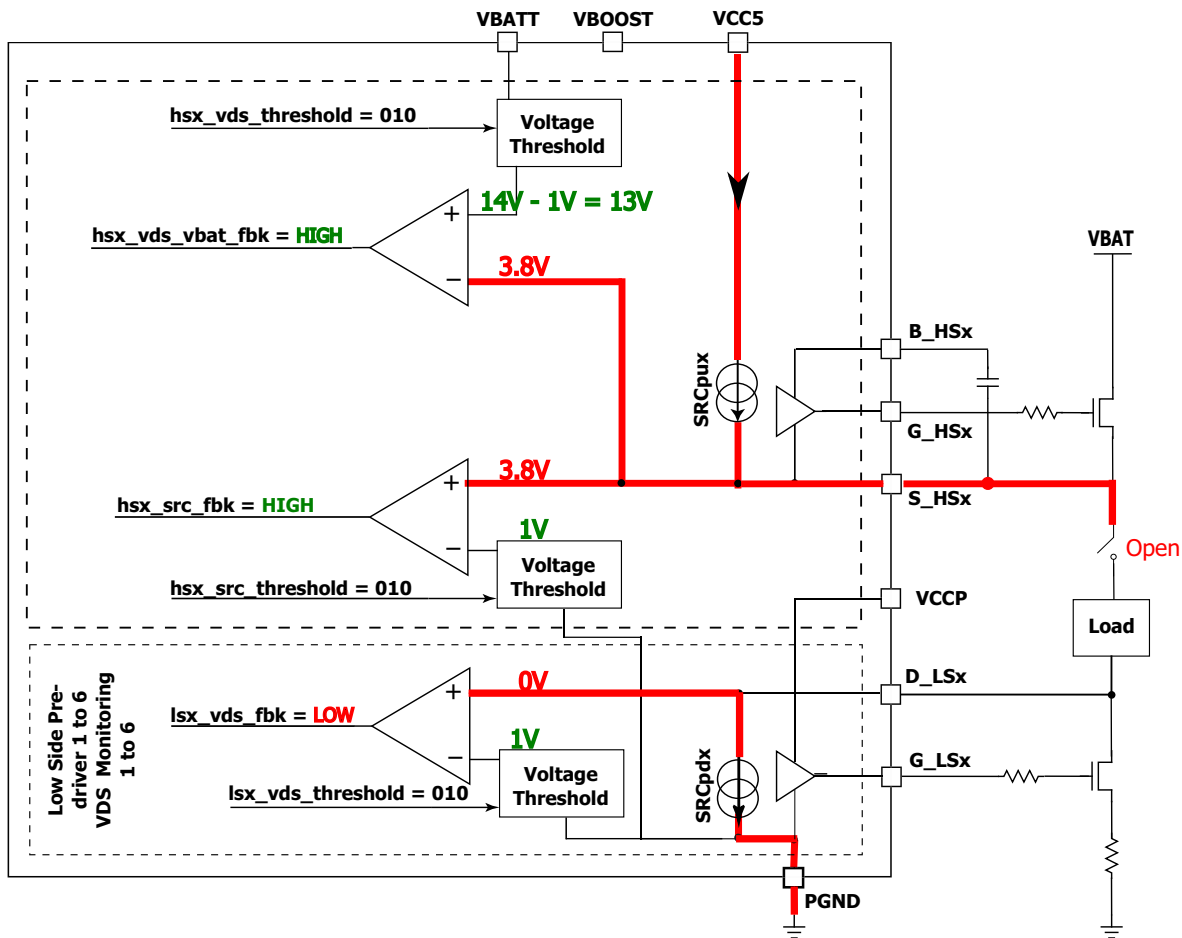


Figure 8. Open Load

If one of the sides of the load is not connected properly, there is no current path between S_{HSx} and D_{LSx}. The voltage on D_{LSx} is forced to ground, because of the SRC_{PDX} current pull-down. The diagnostic fails, because the low-side V_{DS} feedback is low.

Table 8. OpenLoad Truth Table

Error Case	LS _x _vds_fbk	HS _x _src_fbk	Hsx_vds_Vbat_fbk	S _{HSx} voltage V _{BAT}	D _{LSx} voltage
Normal mode	1	1	1	3.8	3.8
OpenLoad on Low-side	0	1	1	3.8	0
OpenLoad on How-side	0	1	1	3.8	0

5.1.6 Faults Not Detected in Idle Phase

There are different cases that cannot be detected in the idle phase:

- High-side V_{BAT} or V_{BOOST} open: not possible to be detected since both are OFF in idle phase
- LS open: not possible to be detected since it is OFF in idle phase
- Short between load pins: not possible to detect, because it allows the bias current to pass through

All these faults are detected in the actuation mode only.

Diagnostic Descriptions

5.2 Actuation Phase

The bias voltage used for idle diagnostics is kept ON, to predict the voltage on each pin even if the MOSFETs are OFF. In this case, when the MOSFETs are OFF, there is a 3.8 V voltage on the high-side source. In each case, if an error occurs, the MC33816 turns bank 1 OFF, keeps it OFF, and sets the Status_reg_uc0 register (0x105) bit 6 high until the MCU writes a 1 to the control register bit 6.

5.2.1 Actuation Diagnostics Peak and Hold phase (HS Boost OFF, HS Bat ON, LS ON)

5.2.1.1 Normal Mode

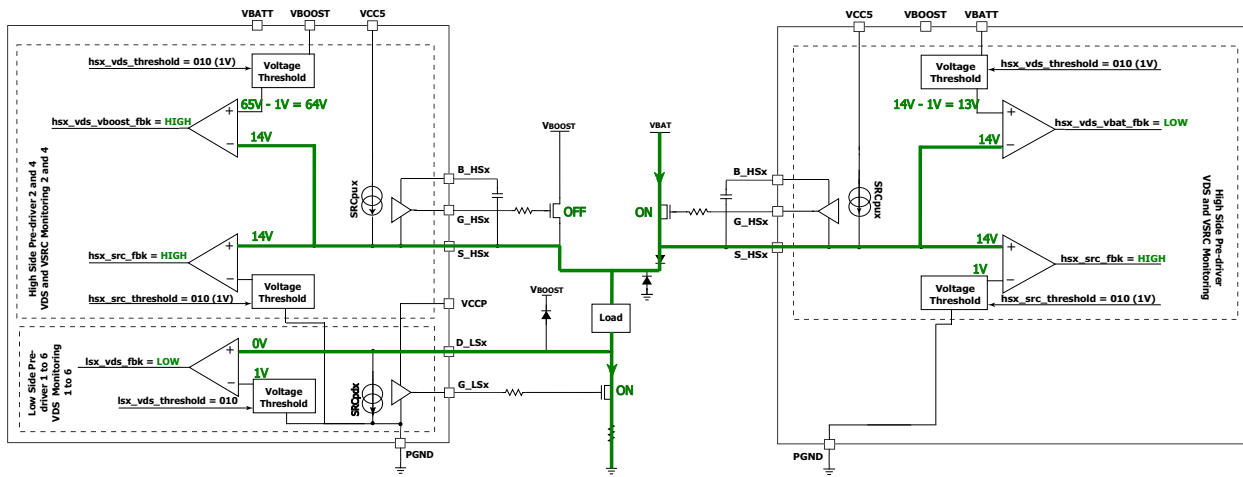


Figure 9. Normal Mode Peak & Hold

During peak and hold phase, the low-side is fully ON and V_{BAT} high-side is controlled in PWM to regulate the current inside the injector.

To have a device as flexible as possible, detection error during automatic diagnostics is configurable for each low-side and high-side. To configure which case will lead the device to an error, it is necessary to set the registers "Error_table" for each low-side V_{DS} , high-side V_{DS} , and high-side S_{RC} where diagnostics are needed (refer to [Diagnostics Configuration Registers](#)). In Normal mode, the 33816 comparator outputs should be in the following state:

Table 9. Actuation in Normal Mode Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	1	1

Diagnostic Descriptions

5.2.1.2 High-side (Bat or Boost) Source Shorted to GND

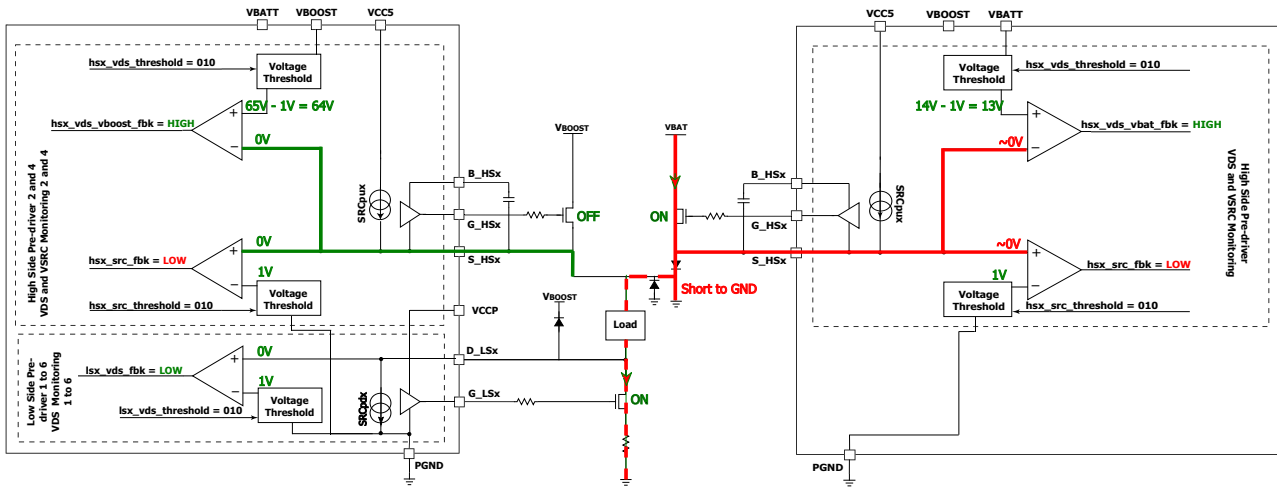


Figure 10. High-side Source Shorted to GND

When S_HSx shorts to GND, the 33816 detects an overcurrent, due to the V_{DS} monitoring on the V_{BAT} high-side. The high-side shuts down as soon as the current is substantial enough to generate a higher V_{DS} drop across the MOSFET than the threshold. In this case, it's important to set a threshold (1.0 V, in this case) and a filter time to the lowest value allowed by the application, to quickly detect it (refer to [Filter Time](#)). The automatic diagnostic fails, because high-side V_{DS} feedback is high.

Table 10. High-side Source Shorted to GND Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	1	1
S_HSx V_{BAT} or V_{BOOST} GND Short	0	0	1	1	0

This case is also applicable when there is a short between the two load pins, substantial current flows inside V_{BAT} HS and LS until the difference between drain and source is higher than the threshold.

5.2.1.3 High-side V_{BOOST} Short Drain Source

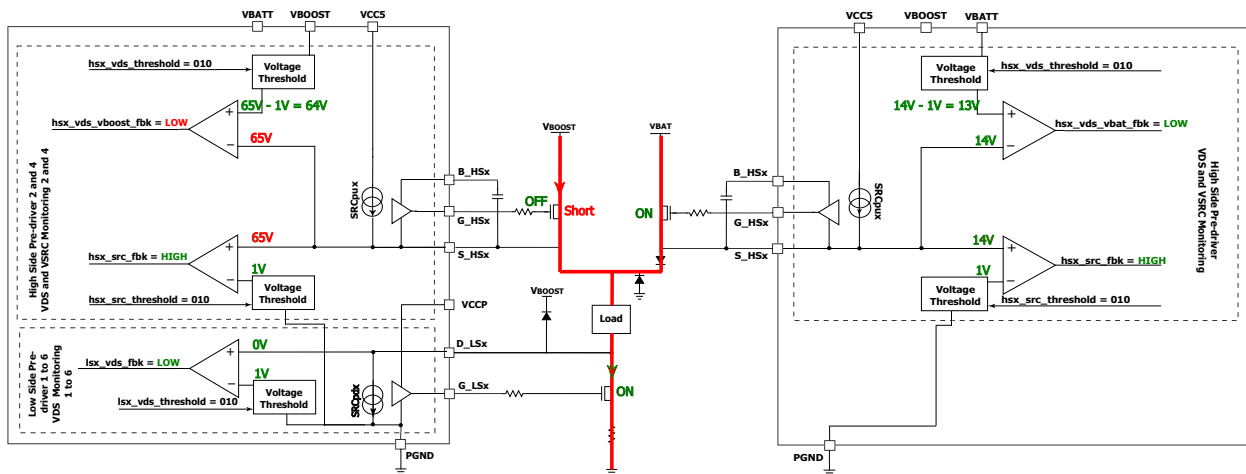


Figure 11. High-side V_{BOOST} Shorted Drain Source

Diagnostic Descriptions

During a peak and hold phase, V_{BOOST} high-side should be OFF, but if there is a short-circuit between the drain and source, the voltage on the V_{BOOST} high-side source rises to V_{BOOST} . The automatic diagnostic fails, because V_{DS} on the V_{BOOST} high-side is low.

Table 11. High-side V_{BOOST} Drain Source Shorted Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	1	1
HSvboot Drain Source short	0	1	0	0	1

5.2.1.4 High-side V_{BAT} Open

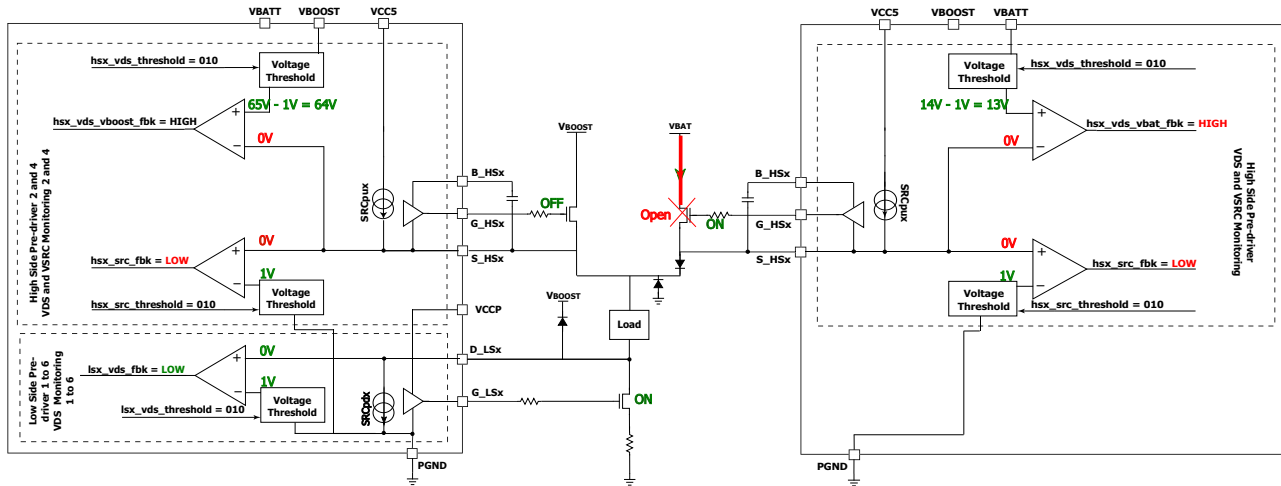


Figure 12. High-side Open

During peak and hold phase, high-side V_{BAT} is ON. If it's open or not controlled properly, S_{HSx} voltage will be lower than expected. The automatic diagnostic fails because on V_{BAT} high-side, the V_{DS} feedback is high and V_{SRC} feedback is low.

Table 12. High-side V_{BAT} Open Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	1	1
HS vbat open	0	0	1	1	0

This case is only detectable in actuation mode.

Diagnostic Descriptions

5.2.1.5 Low-side Open

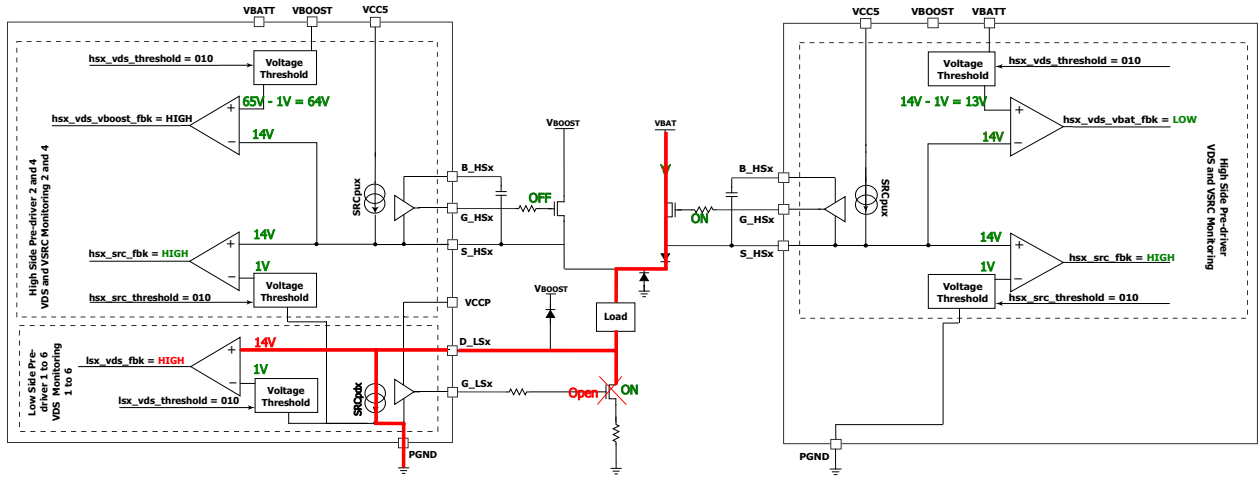


Figure 13. Low-side Open

With the low-side open, current on the D_LSx pin flows through the load to the internal pull-down (SCR_PDX) and the voltage rises to V_{BAT}. Automatic diagnostics fail, because the low-side V_{DS} feedback is high.

Table 13. Low-side Open Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	1	1
LS Open	1	1	0	1	1

This is one case only detectable in actuation mode.

5.2.1.6 Drain Low-side Shorted to V_{BAT} or V_{BOOST}

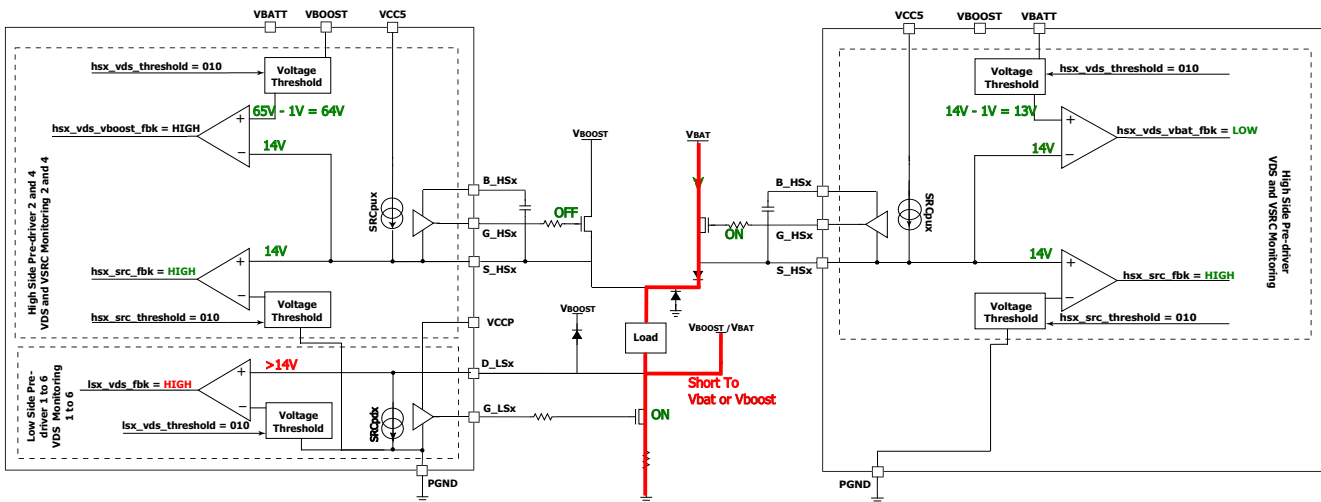


Figure 14. Drain Low-side Shorted

When the low-side drain is shorted to V_{BAT} or V_{BOOST} (low probability case), the voltage on D_LSx rises to V_{BAT}/V_{BOOST}. Voltage thresholds and filter times must be set to the lowest value allowed by the application, to detect the error as fast as possible. The automatic diagnostic fails, because the low-side V_{DS} feedback is high.

Table 14. D_LS Battery Short Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	1	1
D_LS Batt short Depending on external MOS behavior	1	1	0	1	1

5.2.1.7 Cases Undetectable During Peak and Hold Phase

There are different cases that can't be detected during peak and hold phase:

- Drain low-side shorted to GND: not detectable since the low-side is ON, in this case (detectable in idle phase)
- High-side V_{BAT} drain source shorted: not detectable since the high-side is ON, in this case (detectable in idle phase)
- High-side V_{BOOST} open: not detectable since the high-side V_{BOOST} is OFF in this mode (detectable during V_{BOOST} phase)

5.2.2 Actuation Diagnostics Boost Phase (HS Boost ON, HS Bat ON, LS ON)

During Boost phase, boost voltage is used to turn the injector ON as fast as possible, high-side V_{BOOST} and low-side are ON. The high-side V_{BAT} source needs to be turned ON, to avoid errors during diagnostics, which has no impact on the application. Another option would be to disable automatic diagnostics on the high-side V_{BAT} source during boost phase.

In this example, the MC33816 automatic diagnostics are configured using instruction “endiags” (refer to [Application Source Code](#)). During actuation phase, automatic diagnostics monitor HS V_{BAT} V_{DS}, HS V_{BAT} V_{SRC}, HS V_{BOOST} V_{DS}, and LS V_{DS} continuously. To simplify the diagnostics code, HS V_{BAT} is kept ON during Boost phase to avoid unwanted errors on the V_{BAT} source.

5.2.2.1 Normal Mode

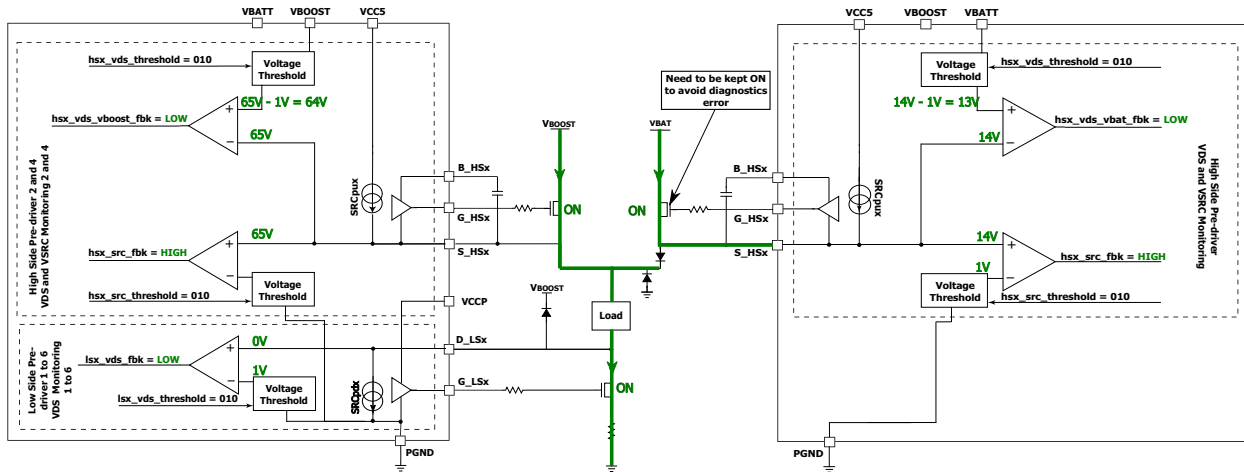


Figure 15. Boost Phase Normal Mode

During boost phase, the high-side boost is fully ON to reach boost current as fast as possible, high-side V_{BAT} is ON (for diagnostic purposes), and the low-side is fully ON. As with the peak and hold phase, the high-side V_{BOOST} error table must be set-up accordingly (see [Diagnostics Configuration Registers](#)).

Table 15. Boost Phase Normal Mode Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	0	1

Diagnostic Descriptions

5.2.2.2 High-side Boost Source Shorted to GND

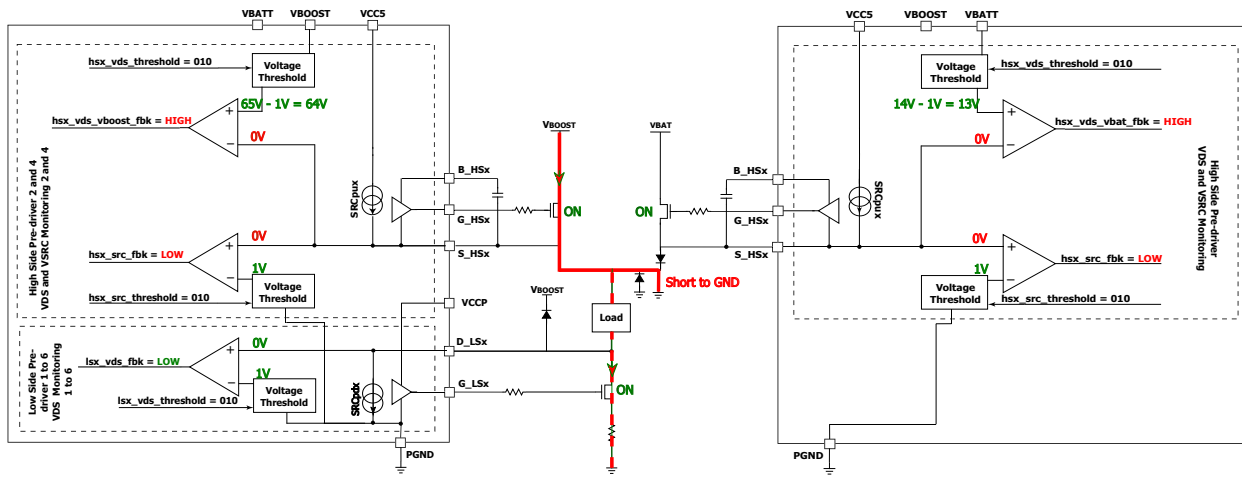


Figure 16. High-side Source Shorted to GND

The same behavior as in the Peak and Hold phase except this time the short is from V_{BOOST} to GND. The comparator threshold must be set as low as possible to detect the overcurrent faster and avoid any damage to the MOS. The automatic diagnostic on high-side V_{BOOST} fails because V_{DS} monitoring is high.

Table 16. High-side Boost Source Shorted to GND Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	0	1
HSvbat Drain Source short	0	0	1	1	0

5.2.2.3 High-side V_{BOOST} Open

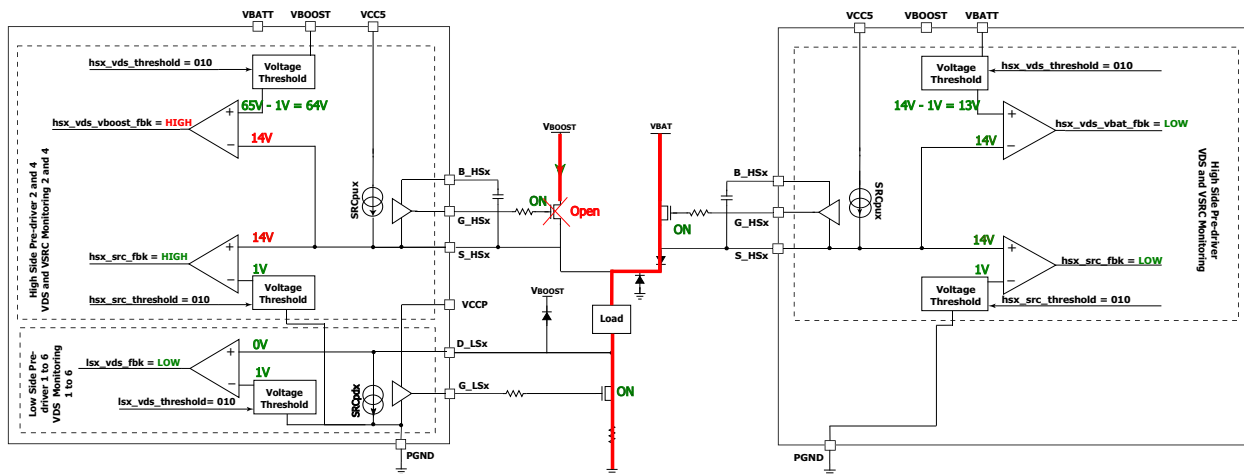


Figure 17. High-side V_{BOOST} Open

When V_{BOOST} high-side is open, the voltage on S_{HSx} floats and forced to 0 V, due to the parasitic leakage on the S_{HSx} pin. The automatic diagnostic on high-side V_{BOOST} fails because V_{DS} feedback is high.

Table 17. High-side Boost Open Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	0	1
HS vboot open	0	1	0	1	1

This case is undetectable in idle phase.

5.2.2.4 Low-side Open

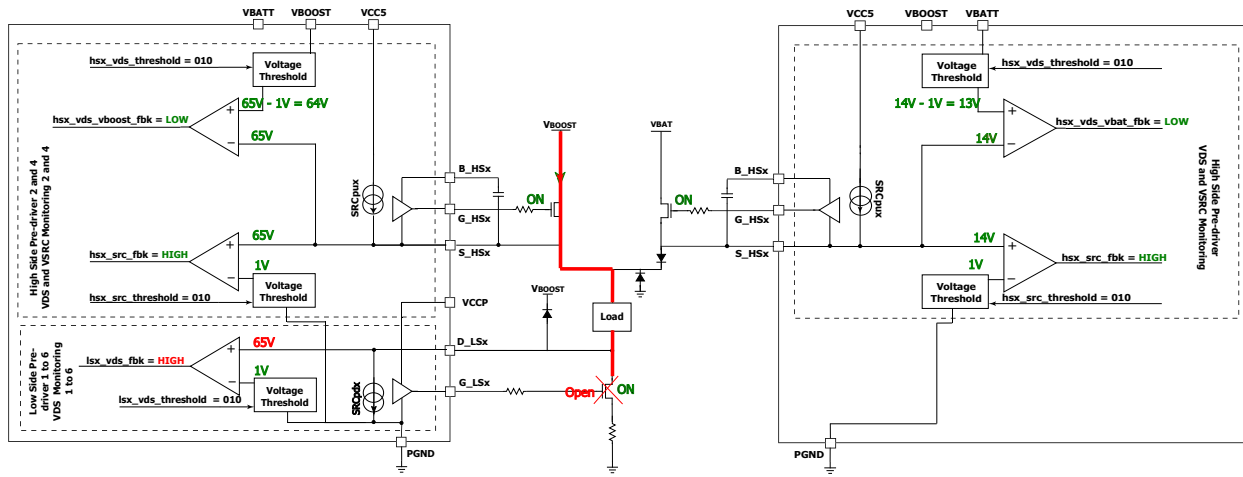


Figure 18. Low-side Open

When the low-side is not connected properly, the voltage on D_LSx is around a V_{BOOST} of 65 V. The automatic diagnostic fails due to V_{DS} feedback on the low-side.

Table 18. Low-side Open Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	0	1
LS open	1	1	0	0	1

This case is undetectable in idle phase.

Diagnostic Descriptions

5.2.2.5 Drain Low-side Shorted to V_{BAT} or V_{BOOST}

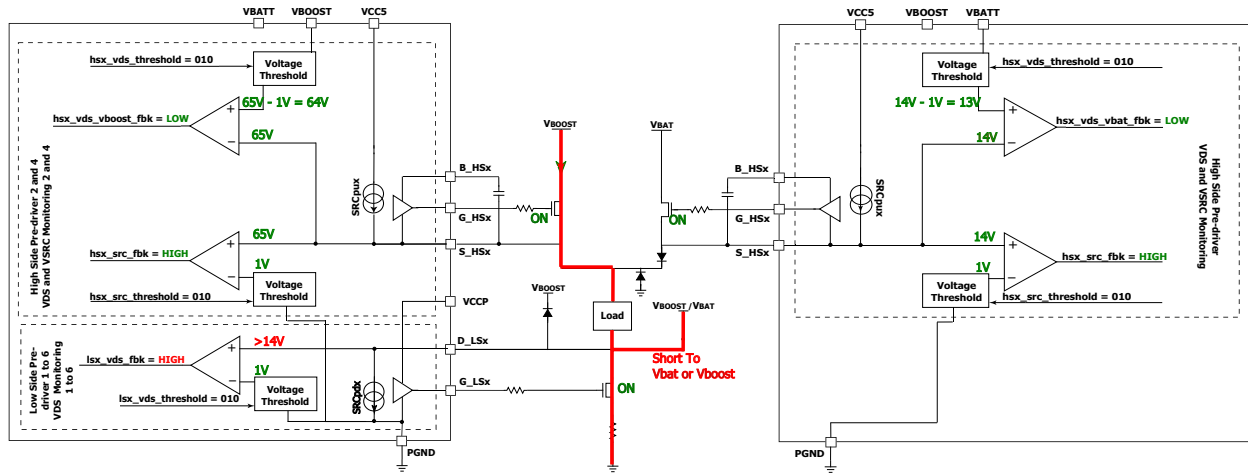


Figure 19. Drain Low-side Shorted to V_{BAT} or V_{BOOST}

This is the same behavior as in the Peak and Hold phase, when the drain low-side is shorted to V_{BAT} or V_{BOOST} (Low probability), with a short to GND on V_{BOOST} or V_{BAT}. The automatic diagnostic fails, because the voltage on D_LSx is higher than the V_{DS} threshold.

Table 19. Drain Low-side Shorted to V_{BAT} or V_{BOOST} Truth Table

Error Case	LSx_vds_fbk	HSx_src_vbat_fbk	Hsx_vds_Vbat_fbk	HSx_vds_Vboost_fbk	HSx_vsrc_Vboost_fbk
Normal mode	0	1	0	0	1
D_LS Boost/Bat short	1	1	0	0	1

5.2.2.6 Cases Undetectable During Boost Mode

There are different cases undetectable in the Boost phase:

- Drain low-side shorted to GND: not detectable, since the low-side is ON in this case (detectable in the idle phase)
- High-side V_{BAT} or V_{BOOST} drain source shorted: not detectable, since in this case, high-side is ON (detectable in the idle phase)
- High-side V_{BOOST} open: not detectable, since the high-side V_{BOOST} is OFF in this mode (detectable during the V_{BOOST} phase)
- A short on the high-side V_{BAT} source S_HSx (before diode): the high-side V_{BAT} is OFF in this mode, but detectable during the idle phase

6 Software

6.1 Interrupt State Machine

The following state diagrams describe how the MCU knows which interrupt occurred and which fault has been detected during both automatic and software interrupts.

For injectors actuation and DCDC state diagram, refer to AN4849.

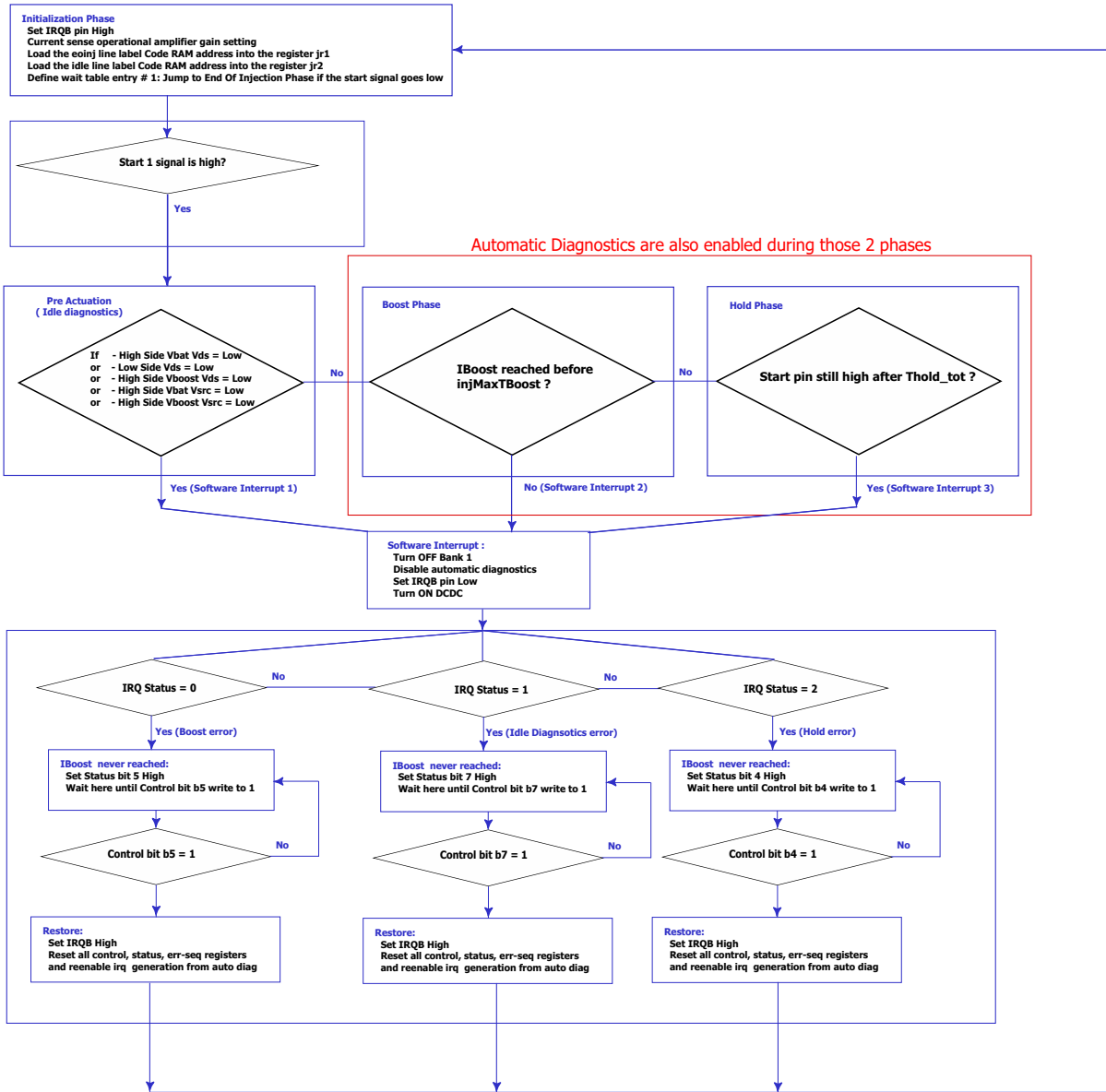


Figure 20. Software Interrupt State Machine

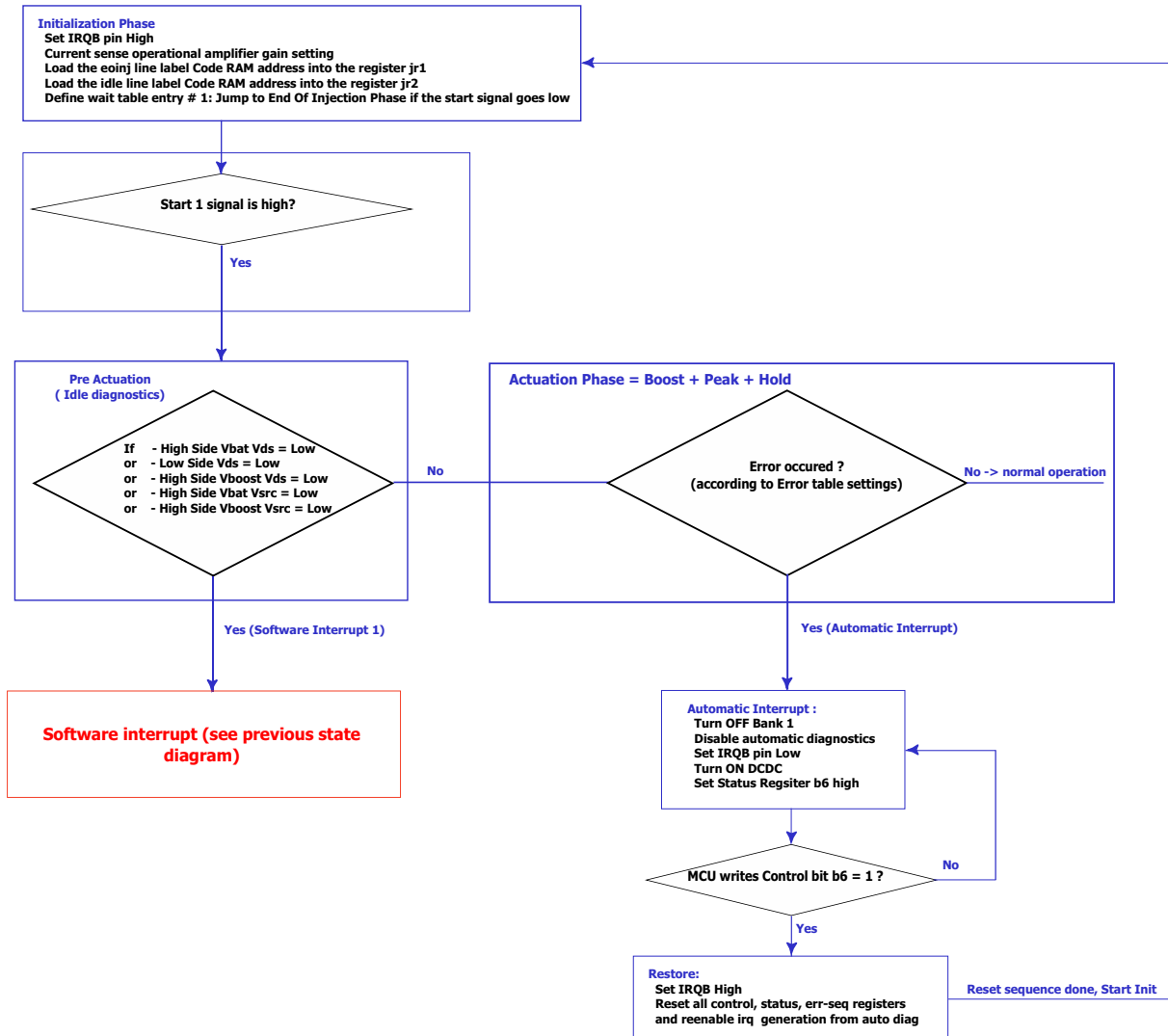


Figure 21. Automatic Interrupt State Machine

Software

6.2 General Registers Setup

Unless specified, use the register settings described in AN4849. Only registers related to diagnostics and interrupts are described in the following chapter.

6.2.1 Main Configuration Registers

Table 20. Driver_config Register (0x1C5)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	hs5_ls36_ovr	vccp_ext_en	ls7_ovr	vboost_mon_en	vboost_disabl_e_en	over_temp_irq_en	drv_en_irq_en	vboost_irq_en	vcc5_irq_en	vccp_irq_en	iret_en	irq_uc1_ch2_en	irq_uc0_ch2_en	irq_uc1_ch1_en	irq_uc0_ch1_en	irq_mcu_en
Value	X	X	X	X	X	X	X	X	1	X	X	X	X	X	X	1

This register doesn't need to be set for the diagnostic on the external MOSFET, since it is handled in the microcode directly. If an error is detected, it forces IRQB low using the microcode. The return address (iret) is also determined in the microcode.

As an example, set vcc5_irq_en to '1', to force IRQB low in cases of undervoltage on Vcc5. When the undervoltage is gone, the IRQB pin is kept low until the user writes a '1' in the uv_vcc5 bit (Driver_status register (0x1D2)).

6.2.2 6.1.2 IO Configuration Registers

This register (one for each microcore) selects the feedback by which each microcore is enabled. Setting the bit to '1' generates an interrupt towards UcXChY, in case an error is detected on the HSx or LSx feedback.

Table 21. Fbk_sens_uc0ch1 Register (0x180)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	ls6_vds_sens	ls5_vds_sens	ls4_vds_sens	ls3_vds_sens	ls2_vds_sens	ls1_vds_sens	hs5_vsrc_sens	hs5_vds_sens	hs4_vsrc_sens	hs4_vds_sens	hs3_vsrc_sens	hs3_vds_sens	hs2_vsrc_sens	hs2_vds_sens	hs1_vsrc_sens	hs1_vds_sens
Value	0	1	0	0	1	1	0	0	0	0	0	0	1	1	1	1

In this particular application (see the schematics in KIT33816AEEVM), microcore 0 Channel 1 controls HS1 as high-side V_{BAT} and HS2 as high-side V_{BOOST} , LS1 and LS2. As show in table [Table 21](#), an interrupt is generated if an error occurs on LS2 V_{DS} , LS1 V_{DS} , HS2 V_{DS} , HS1 V_{DS} , HS2 V_{SRC} , and HS1 V_{SCR} .

Software

6.2.2.1 Threshold settings

Each comparator threshold is set on three bits. The V_{DS} and V_{SRC} thresholds are defined by registers 0x18A and 0x18B, for the high-side pre-drivers, and by the $V_{ds_threshlod_ls_1}$ (0x18C) for the low-side pre-drivers.

As described during fault description, these threshold must be set according to the external MOSFET and maximum current level used in the application. As with KIT33816AEEVM, $R_{DS(ON)}$ MOSFET ~40 m Ω (worst case condition). The maximum current used in this application is 16.09 A, and overcurrent detection (using V_{DS} monitoring) must be set at around 30% higher than max current allowed (20 A).

Table 22. V_{DS} and V_{SRC} Monitoring Typical Threshold Selection

Threshold(2:0)	VDS (V) (LS and HS)	VSRC (V) (only HS)
000	0.00	0.0
001	0.5	0.5
010	1	1
011	1.5	1.5
100	2.0	2.0
101	2.45	2.5
110	2.95	3.0
111	3.45	3.5

High-side V_{DS} Threshold Calculation

V_{DS} Threshold (HS) = Overcurrent $\times R_{DS(ON)}$ = 20 A \times 0.040 Ω = 0.8 V \rightarrow **1.0 V** threshold selected. In this case, overcurrent = 1.0 V / 0.04 Ω = 25 A.

Table 23. $V_{ds_threshold_hs}$ Register (0x18A)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Reserved	Vds thr Hs5			Vds thr Hs4			Vds thr Hs3			Vds thr Hs2			Vds thr Hs1		
Value	0	xxx			xxx			xxx			010			010		

Low-side V_{DS} Threshold Calculation

Low-side the V_{DS} monitoring is done between D_LSx and GND, sense resistance must be included in the calculation.

V_{DS} threshold (LS) = Overcurrent $\times (R_{DS(ON)} + R_{SENSE})$ = 20 A \times (0.040 Ω + 0.015 Ω) = 1.1 V \rightarrow **1.0 V** threshold selected, in this case overcurrent = 1.0 V / 0.055 Ω = 18 A.

Table 24. $V_{ds_threshold_ls_1}$ Register (0x18C)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Reserved	Vds thr Ls5			Vds thr Ls4			Vds thr Ls3			Vds thr Ls2			Vds thr Ls1		
Value	0	xxx			xxx			xxx			010			010		

Software

High-side SRC threshold

V_{SRC} is used mostly during idle phases to understand the type of fault present. It is better to keep the "detection threshold" far from the polarization condition. During actuation in this application, recirculation is done through a diode, keeping the voltage of the HS source below ground. In this case, any V_{SRC} voltage is ok, to prevent false diagnostics. In order to avoid detecting noise and to be far from the 3.8 V threshold, the MC33816 V_{SRC} threshold is set to 1.0 V

Table 25. Vsrc_threshold_hs Register (0x18B)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Reserved	Vsrc thr Hs5			Vsrc thr Hs4			Vsrc thr Hs3			Vsrc thr Hs2			Vsrc thr Hs1		
Value	0	xxx			xxx			xxx			001			001		

6.2.3 Channel 1 Configuration Registers

Unless specified, use the same settings specified in the AN4849.

Table 26. Ctrl_reg_uc0 Control Registers for the Microcore 0 (0x101, 0x121)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	control_register_shared								control_register							
Value	xxxxxxxx								00000000							

control_register: Control bits 4,5,6,and 7 are used to control the turn ON of the bank after a fault occurs

- B4: if START pin is still high after t_{HOLD_TOT} is reached (see [Application Source Code](#))
- B5: if I_{BOOST} is not reached before the specified time
- B6: if errors are detected during actuation (automatic diagnostics)
- B7: if errors are detected during pre-actuation phase (idle diagnostics)

Entry point for each microcode as specified, corresponds to the location in the CRAM where each uC starts.

Table 27. Uc0_entry_point Registers (0x10A, 0x12A)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Reserved						entry_point_address									
Value	000000						100110000									

With the code provided, uc0 channel 1 starts line152 label "init0", interrupt code should not be taken in account in the entry code.

Table 28. Uc1_entry_point Registers (0x10B, 0x12B)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Reserved						entry_point_address									
Value	000000						000001000									

With code provided, uc1 channel starts line 091 label "init1".

Software

It is required to specify the location in the CRAM, because the automatic interrupt is handled here.

Table 29. Diag_routine_addr Registers (0x10C, 0x12C)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Reserved				diagnosis_routine_address_uc1						diagnosis_routine_address_uc0					
Value	0000				Xxxxxx						000000					

- diagnosis_routine_address_uc0: Automatic diagnostics are located at line 0 (label irq_auto)
- diagnosis_routine_address_uc1: Not used in this example

The same settings on software interrupt are needed to specify the location in the CRAM where SW interrupts are handled.

Table 30. Sw_interrupt_routine_addr Registers (0x10E, 0x12E)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	sw_irq_falling_edge_start_uc1	sw_irq_rising_edge_start_uc1	sw_irq_falling_edge_start_uc0	sw_irq_rising_edge_start_uc0	software_interrupt_routine_address_uc1						software_interrupt_routine_address_uc0					
Value	x	x	x	x	xxxxxx						000111					

- software_interrupt_routine_address_uc0: Line 7 in the CRAM
- software_interrupt_routine_address_uc1: Not used in this example
- sw_irq_rising_edge_start_uc0: Not used in this example
- sw_irq_falling_edge_start_uc0: Not used in this example.

Software

6.3 Diagnostics Configuration Registers

6.3.1 LS1 & LS2 Output Register

6.3.1.1 Filter Time

These registers define the automatic diagnostics filtering. Values depend on noise in the application and MOSFET switching time to get stable for reliable feedback when diagnostics start.

Table 31. Lsx_diag_config1 Registers (0x140, 0x143, 0x146, 0x149, 0x14C, 0x14F)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Reserved		filter_t ype	filter_length						disable_window						
Reset	00		0	111011						1011010						

- filter_type: Set to 0, in this case, means any different sample resets the filter counter
- filter_length: The filtering time is: $t_{FTN} = t_{CK} \times (5 + 1) = 1/6 \text{ MHz} \times 6 = 1 \mu\text{s}$
- disable_window: this 7-bit parameter configures a time period during which any check on the LSx_Vds_feed signal is disabled after any change on the output_command signal. $t_{DTL} = t_{CK} \times (14 + 4) = 1/6 \text{ MHz} \times 18 = 3.0 \mu\text{s}$

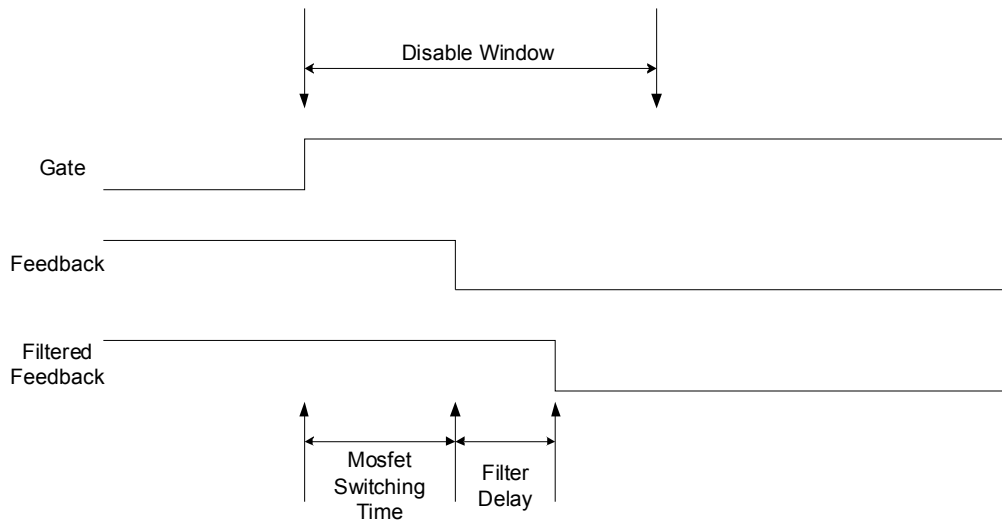


Figure 22. Filter Time and Disable Windows Diagram

6.3.1.2 Error Table

Using the [Diagnostic Descriptions](#) section, error tables can be easily generated,

Table 32. Lsx_diag_config2 Registers (0x141, 0x144, 0x147, 0x14A, 0x14D, 0x150)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Reserved												error_table			
Reset	000000000000												1001			

- error_table: this 4-bit parameter defines the logical value of an error signal, issued from the output and the related V_{DS} feedback signal. This table defines the output of the coherency check between the driven output and the acquired feedback; a logic one value means there is no coherency in the check, and then an error signal towards the microcore should be generated

Table 33. Error Table for Both Low-sides

	output_command = 0 (Pre-driver switched OFF)	output_command = 1 (Pre-driver switched ON)
lsx_vds_fbk = 0 (V_{DS} below threshold)	error_table (0) = 1	error_table (2) = 0 (OK)
lsx_vds_fbk = 1 (V_{DS} above threshold)	error_table (1) = 0 (OK)	error_table (3) = 1

Normal mode in this application:

- Low-side is ON and the V_{DS} comparator should be low
- Low-side is OFF and the V_{DS} comparator should be high

6.3.2 HS1 / HS2 Output Register

6.3.2.1 Filter Time

Use the same filtering as the low-side, since the same MOSFET and slew rates are used for both.

Table 34. Hsx_diag_config_1 Registers (0x153, 0x156, 0x159, 0x15C, 0x15F)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Reserved		Filter_type	filter_length						disable_window						
Reset	00		0	111011						1011010						

- filter_type: Set to 0, in this case, means any different sample resets the filter counter
- filter_length: The filtering time is: $t_{FTN} = t_{CK} \times (5 + 1) = 1/6 \text{ MHz} \times 6 = 1 \mu\text{s}$
- disable_window: this 7-bit parameter configures a time period during which any check on the LSx_Vds_feed signal is disabled after any change on the output_command signal. $t_{DTL} = t_{CK} \times (14 + 4) = 1/6 \text{ MHz} \times 18 = 3.0 \mu\text{s}$

6.3.2.2 Error Table

HS1 (VBAT) error table

Table 35. Hsx_diag_config_2 Registers (0x154, 0x157, 0x115A, 0x15D, 0x160)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Reserved								error_table_src			error_table_vds				
Reset	00000000								0110			1001				

Table 36. Error Table for High-side V_{DS}

	output_command = 0 (Pre-driver switched OFF)	output_command = 1 (Pre-driver switched ON)
hsx_vds_fbk = 0 (V_{DS} below threshold)	error_table_vds (0) = 1	error_table_vds (2) = 0
hsx_vds_fbk = 1 (V_{DS} above threshold)	error_table_vds (1) = 0	error_table_vds (3) = 1

Normal mode in this application:

- High-side is ON and the V_{DS} comparator should be low
- High-side is OFF and the V_{DS} comparator should be high

Software

Table 37. Error Table for High-side V_{SRC}

	output_command = 0 (Pre-driver switched OFF)	output_command = 1 (Pre-driver switched ON)
hsx_src_fbk = 0 (V_{SRC} below threshold)	error_table_src (0) = 0	error_table_src (2) = 1
hsx_src_fbk = 1 (V_{SRC} above threshold)	error_table_src (1) = 1	error_table_src (3) = 0

Normal mode in this application:

- High-side is ON and the V_{SRC} comparator should be high
- High-side is OFF and the V_{SRC} comparator should be low

HS2 (VBOOST) error table

Table 38. Hsx_diag_config_2 Registers (0x154, 0x157, 0x115A, 0x15D, 0x160)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Name	Reserved							error_table_src				error_table_vds				
Reset	00000000							0100				1001				

	output_command = 0 (Pre-driver switched OFF)	output_command = 1 (Pre-driver switched ON)
hsx_vds_fbk = 0 (V_{DS} below threshold)	error_table_vds (0) = 1	error_table_vds (2) = 0
hsx_vds_fbk = 1 (V_{DS} above threshold)	error_table_vds (1) = 0	error_table_vds (3) = 1

	output_command = 0 (Pre-driver switched OFF)	output_command = 1 (Pre-driver switched ON)
hsx_src_fbk = 0 (V_{SRC} below threshold)	error_table_src (0) = 0	error_table_src (2) = 1
hsx_src_fbk = 1 (V_{SRC} above threshold)	error_table_src (1) = 0	error_table_src (3) = 0

V_{BOOST} high-side source detection is different in this application from V_{BAT} since S_HSVbat and S_HS_VBoost are shorted together through a diode. If V_{BAT} high-side is ON, voltage on the V_{BOOST} source high-side is equal to V_{PWR} - diode. Consequently, the 33816 should not detect an error on high-side V_{BOOST} if command = 0 and source feedback = 1.

Application Source Code

7 Application Source Code

The following microcode can be directly downloaded from the NXP web site (see [KIT33816AEEVM](#)). Using the IDE and SPIGEN, the microcode can be downloaded to the MC33816.

7.1 Injection Banks Management Source Code

```
#include "AN_Diag_ch1.def";
*****
*                                     Copyright (c) NXP 2016 *
* File Name: Pierre_test_4inj.dfi                                           *
* Current Revision: 1.0                                                     *
* Purpose: MC33816 example - 1 Bank diagnostic                             *
* Description: MC33816 Channel 1 main function provide peak and hold current *
*              profile for Uc0Ch1 and use idle and automatic diagnostics *
*              Uc1Ch1 provide peak and hold without diagnostics*
*
*
* REV  AUTHOR      DATE      DESCRIPTION OF CHANGE
* ---  -
* 1.0  b16868      2014/03/25  - initial coding
*
*****

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* ### Channel 1 - uCore0 controls the injectors 1 ###

* Constant definition
#define HSBoost_B1 hs2;
#define HSBAT_B1 hs1;
#define LS1_B1 ls1;
#define LS2_B1 ls2;

##### STATUS REGISTER #####
* This bit must be set to 1 if the Iboost current is never reached during the boost phase
#define BoostErrorBit b5;
* This bit must be set to 1 the sequencer is currently executing the Automatic interrupt routine
#define AutoIrqBit b6;
* This bit must be set to 1 the sequencer is currently executing the Idle Diag interrupt routine
#define IdleIrqBit b7;
* This bit must be set to 1 if start pin stays high longer than 10ms
#define HoldErrorBit b4;

##### FLAGS #####
* This flag is sent to the DCDC sequencer. It must be active for the whole period the boost voltage is used
* When the boost voltage is used, the DCDC must be deactivated
* flag = 0 => boost voltage is used, DCDC must be deactivated
* flag = 1 => boost voltage not used, DCDC can be active
```

Application Source Code

```
#define BstFlag b0;

##### CONTROL REGISTER #####
* During the interrupt routine, the sequencer wait for this bit to be set to '1' before resuming execution of application
code
#define AutoDiagResetBit b6;
* During the interrupt routine, the sequencer wait for this bit to be set to '1' before resuming execution of application
code
#define IdleDiagResetBit b7;
* During the interrupt routine, the sequencer wait for this bit to be set to '1' before resuming execution of application
code
#define BoostResetBit b5;
* During the interrupt routine, the sequencer wait for this bit to be set to '1' before resuming execution of application
code
#define HoldResetBit b4;

##### ALU registers #####
#define IRQ_stat_Reg r0;

*****
*
* AUTOMATIC INTERRUPT
*
*****
irq_auto:      stos off off off;          * Disable drivers
               endiaga diagoff;        * Disable automatic diagnostic
               stirq low;              * Set the low IRQB pin
               stf high BstFlag;       * Set flag0 high DCDC active
               stsrb high AutoIrqBit;  * Set status register bit 5 when automatic diagnosis interrupt trig

auto_waitEnable:jcrr auto_waitEnable AutoDiagResetBit low; * the sequencer is stuck here until the bit of the control
register is set to '1' b6
               ldjrl restore;          * Load restore to jrl to do a jump far
               jmpf jrl;               * Jump to restore

*****
*
* SOFTWARE INTERRUPT
*
*****
irq1_sw:      stos off off off;          * Disable drivers
               endiaga diagoff;        * Disable automatic diagnostic
               stirq low;              * Set low the IRQB pin
               stf high BstFlag;       * Set flag0 high to release the DC-DC converter idle mode

               * Check which Sw interrupt occurred BoostErr 0 or Idle Diag Fail 1
               cp irq IRQ_stat_Reg;    * copy the irq status registers to a temp ALU reg
               * This register contains also the sw irq ID
               ldirh 0Ch rst;          * load MSB in ir reg: 0x0C00 in immediate register, to use as mask

for irq status
               and IRQ_stat_Reg;       * extract the sw id from irq status register (bits 11-10)
               jarr Boost_waitEN all0; * if the sw id is 0 => Iboost never reached => go to Boost_waitEN
               * Else => error detected in idle diag=> go to next line => seq

stuck until micro write 1 in control register b8

               ldirh 08h rst;          * load MSB in ir reg: 0x0800 in immediate register, to use as mask

for irq status
               and IRQ_stat_Reg;       * extract the sw id from irq status register (bits 11-10)
               jarr sw_waitEnable all0; * if the sw id is 0 => Means IRQ = b01 => Idle diagnostics fails
               * Else => Hold error => go to next line => idle diag fail

Hold_waitEN:  stsrb high HoldErrorBit;  * Start pin stays higher longer than 10ms
               jcrr Hold_waitEN HoldResetBit low; * Wait here until control bit register is write to 1
               jmpr restore;

sw_waitEnable: stsrb high IdleIrqBit;    * IDle diag fail we set status b8 high to let user know which error
```

Application Source Code

```
occured
    jcurr sw_waitEnable IdleDiagResetBit low; * Wait here until control bit register is write to 1
    jmp restore;

Boost_waitEN:   stsrb high BoostErrorBit;          * Iboost never reached, let user know by setting status register
bit b5
    jcurr Boost_waitEN BoostResetBit low;      * Wait here until control bit register is write to 1

restore:
    stirq high;                                * Set high IRQB pin
    rstreg all;                                * Reset a) control registers
                                                *      b) status regsiter
                                                *      c) err_seq register (status of automatic diagnosis
                                                *      d) re-enables irq generation from automatic diagnosis
    ired restart rst;                          * Clear interrupt queue and restart from init phase

*****
*
*                               INIT PHASE
*****
init0:   stirq high;                            * Set high IRQB pin
         stgn gain8.68 sssc;                    * Set gain amplifier for current feedback 1
         ldjrl eoinj0;                          * Load end of injector in jrl to use jump far
         ldjr2 idle0;                            * Load idle0 in jrl to use jump far
         cwef jrl _start row1;                  * If any start goes low go to eoi

*****
*
*                               IDLE PHASE
*****
idle0:   joslr inje1 start1;                    * Start injector 1 if start1 goes high
         joslr inje2 start2;                    * Start injector 2 if start2 goes high
         jmpf jrl;                               * Jump to end of injection

*****
*
*                               SHORTCUT DEFINITION
*****
inje1:   dfcset HSBAT_B1 LS1_B1 HSBoost_B1;    * Shortcut1 = HSBAT, Shortcut2= LS2_B1, Shortcut3= HSBOOST
         dfcset dacl;                            * use current feedback1
         jmpr idle_diag0;                       * Jump to idle_diag0

inje2:   dfcset HSBAT_B1 LS2_B1 HSBoost_B1;    * Shortcut1 = HSBAT, Shortcut2= LS2_B1, Shortcut3= HSBOOST
         dfcset dacl;                            * use current feedback1
         jmpr idle_diag0;                       * Jump to idle_diag0 (useless here)

*****
*
*                               PRE-ACTUATION DIAG PHASE
*****
idle_diag0:  bias all on;                       * Enable all biasing structures, kept ON even during actuation
            jocr idle_diag_fail0 _sc1v;        * Error detected if Vds of shortcut1 (HS) is low
            jocr idle_diag_fail0 _sc2v;        * Error detected if Vds of shortcut2 (LS) is low
            jocr idle_diag_fail0 _sc3v;        * Error detected if Vds of shortcut3 (Boost) is low
            jocr idle_diag_fail0 _sc1s;        * Error detected if Vsrc of shortcut1 (HS) is low
            jocr idle_diag_fail0 _sc3s;        * Error detected if Vsrc of shortcut3 (Boost) is low
            jmpr boost0;                       * Jump to actuation phase if no failure detected in idle phase

idle_diag_fail0: reqi 1;                       * Go to software subroutine is fault detected in idle phase HSBat
error
```

Application Source Code

```
*****
*                                     BOOST PHASE                               *
*****

boost0:   ldcd rst _ofs keep keep injMaxTBoost c3;      * Start Boost Counter in case Iboost never reached
          load Iboost dac_sssc _ofs;                  * Load Boost current threshold

          cwer peak0 curl row2;                       * Define Wait Table Iboost is reached and jump to peak phase
          cwer boost_err0 tc3 row5;                   * Define Wait Table if actuation longer than injMaxGuard go to
eoinj (added from AN4849)

          stf low BstFlag;                            * Turn OFF the boost during this phase
          stos on on on;                              * Vbat high-side On, Vboost HS On et LS1/2 ON, need to turn ON
HS1 also to avoid diag failure
          endiags on on on on;                       * Enable auto diag

          wait row125;                                * Wait start goes low or Iboost reached or InjMaxTBoost reached

boost_err0: reqi 0;                                  * Go to software subroutine is fault detected in Boost phase,
did not reach Iboost on time (added from AN4849)

*****
*                                     PEAK PHASE                               *
*****

peak0:    ldcd rst _ofs keep keep Tpeak_tot c1;       * Start Tpeak tot counter
          stf high BstFlag;                          * Turn Boost back on
          load Ipeak dac_sssc _ofs;                  * Load the peak current threshold in the current DAC
          cwer bypass0 tc1 row2;                     * Define Wait: Jump to bypass phase when tc1 reaches end of count
          cwer peak_on0 tc2 row3;                    * Define Wait: Jump to peak_on when tc2 reaches end of count
          cwer peak_off0 ocur row4;                  * Define Wait: Jump to peak_off when current is over threshold

peak_on0: stos on on off;                             * Vbat On LS On, if needed Boost HS can stay ON during this phase
          wait row124;

peak_off0: ldcd rst ofs keep keep Tpeak_off c2;      * Load in the counter 2 the length of the peak_off phase
          stos off on off;                          * turn OFF HSvbat keep LS ON
          wait row123;

*****
*                                     BYPASS PHASE                               *
*****

bypass0:  ldcd rst ofs keep keep Tbypass c3;        * Load in the counter 3 the length of the off_phase phase
          stos off off off;                         * turn OFF all HS LS1/2
          cwer hold0 tc3 row4;                      * Define Wait: Jump to hold when tc3 reaches end of count
          wait row14;
```


Application Source Code

```
*****
*                                     HOLD PHASE                               *
*****

hold0:      ldcd rst _ofs keep keep Thold_tot c1;      * load thold tot inside c1
            load Ihold dac_sssc _ofs;                * load hold current inside DAC
            cwer hold_error0 tc1 row2;                * Define Wait: Jump to hold error if start still high after

thold_tot   cwer hold_on0 tc2 row3;                    * Define Wait: Jump to hold on after thold off
            cwer hold_off0 curl row4;                * Define Wait: Jump to hold off when current Ihold reached

hold_on0:   stos on on off;                            * HSvbat ON, LS ON
            wait row124;

hold_off0:  ldcd rst _ofs keep keep Thold_off c2;     * load thold off inside c2
            stos off on off;                          * LS ON
            wait row123;

hold_error0: reqi 2;                                    * If Start high is longer than Thold_tot go to sw interrupt

*****
*                                     END OF INJECTION PHASE                       *
*****

eoinj0:     stos off off off;
            endiags off off off off;                  * disable auto diag
            stf high BstFlag;                         * turn ON DCDC
            jmpf jr2;                                  * jump to idle

#####
#####

*****

* ### Channel 1 - uCore1 controls injectors 3 and 4 without diagnostics ###

* ### Variables declaration ###

* Note: The data that defines the profiles are shared between the two microcores.

* ### Initialization phase ###
init1:      stgn gain8.68 sssc;                        * Set the gain of the opamp of the current measure block 2
            ldjrl eoinj1;                             * Load the eoinj line label Code RAM address into the register jrl
            ldjr2 idle1;                              * Load the idle line label Code RAM address into the register jr2
            cwef jrl _start row1;                      * If the start signal goes low, go to eoinj phase

* ### Idle phase- the uPC loops here until start signal is present ###
idle1:      joslr inj3_start start3;                  * Perform an actuation on inj3 if start 3 (only) is active
            joslr inj4_start start4;                  * Perform an actuation on inj4 if start 4 (only) is active
            jmpf jrl;                                  * If more than 1 start active at the same time(or none), no actuation

* ### Shortcuts definition per the injector to be actuated ###
inj3_start:dfsct hs3 hs4 ls3;                         * Set the 3 shorcuts : VBAT, VBOOST, LS
            jmpr boost1;                              * Jump to launch phase

inj4_start:dfsct hs3 hs4 ls4;                         * Set the 3 shorcuts : VBAT, VBOOST, LS
            jmpr boost1;                              * Jump to launch phase

* ### Launch phase enable boost ###
boost1:     load Iboost dac_sssc _ofs;                * Load the boost phase current threshold in the current DAC
            cwer peak1 ocur row2;                    * Jump to peak phase when current is over threshold
            stf low b0;                               * set flag0 low to force the DC-DC converter in idle mode
            stos off on on;                           * Turn VBAT off, BOOST on, LS on
            wait row12;                               * Wait for one of the previously defined conditions
```

Application Source Code

```

* ### Peak phase continue on Vbat ###
peak1:   ldcd rst _ofs keep keep Tpeak_tot c1;* Load the length of the total peak phase in counter 1
load Ipeak dac_sssc _ofs; * Load the peak current threshold in the current DAC
cwer bypass1 tc1 row2; * Jump to bypass phase when tc1 reaches end of count
cwer peak_on1 tc2 row3; * Jump to peak_on when tc2 reaches end of count
cwer peak_off1 ocur row4; * Jump to peak_off when current is over threshold
stf high b0; * set flag0 high to release the DC-DC converter idle mode

peak_on1: stos on off on; * Turn VBAT on, BOOST off, LS on
wait row124; * Wait for one of the previously defined conditions

peak_off1: ldcd rst ofs keep keep Tpeak_off c2;* Load in the counter 2 the length of the peak_off phase
stos off off on; * Turn VBAT off, BOOST off, LS on
wait row123; * Wait for one of the previously defined conditions

* ### Bypass phase ###
bypass1: ldcd rst ofs keep keep Tbypass c3;* Load in the counter 3 the length of the off_phase phase
stos off off off; * Turn VBAT off, BOOST off, LS off
cwer hold1 tc3 row4; * Jump to hold when tc3 reaches end of count
wait row14; * Wait for one of the previously defined conditions

* ### Hold phase on Vbat ###
hold1:   ldcd rst _ofs keep keep Thold_tot c1;* Load the length of the total hold phase in counter 2
load Ihold dac_sssc _ofs; * Load the hold current threshold in the DAC
cwer eoinj1 tc1 row2; * Jump to eoinj phase when tc1 reaches end of count
cwer hold_on1 tc2 row3; * Jump to hold_on when tc2 reaches end of count
cwer hold_off1 ocur row4; * Jump to hold_off when current is over threshold

hold_on1: stos on off on; * Turn VBAT on, BOOST off, LS on
wait row124; * Wait for one of the previously defined conditions

hold_off1: ldcd rst _ofs keep keep Thold_off c2;* Load the length of the hold_off phase in counter 1
stos off off on; * Turn VBAT off, BOOST off, LS on
wait row123; * Wait for one of the previously defined conditions

* ### End of injection phase ###
eoinj1:  stos off off off; * Turn VBAT off, BOOST off, LS off
stf high b0; * set flag0 to high to release the DC-DC converter idle mode
jmpf jr2; * Jump back to idle phase

* ### End of Channel 1 - uCore1 code ###
```

Application Source Code

7.2 DC-DC and Fuel Pump Source Code

```
#include "AN_Diag_ch2.def";
*****
*                                     Copyright (c) NXP 2014 *
* File Name: Pierre_test_4inj.dfi *
* Current Revision: 1.0 *
* Purpose: MC33816 example - 4 injectors control with Peak & Hold *
* Description: MC33816 Channel 1 main function provide peak and hold current *
*              profile for Uc0Ch1 and Uc1Ch1 *
* File created by: NXP Analog, Tempe *
*
* UPDATE HISTORY *
* REV  AUTHOR      DATE      DESCRIPTION OF CHANGE *
* ---  - - - - -  - - - - -  - - - - - *
* 1.0  b16868     2014/03/25  - initial coding *
*
*****

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* ### Channel 2 - uCore0 controls the DCDC ###

##### INIT #####
init0:    stgn gain5.8 ossc;
          load Iboost_L dac_osscc_ofs; *load DAC 4 L with low Vboost current
          load Iboost_H dac4h4n_ofs; *load DAC 4H with high Vboost current
          stdm null; *Set DAC access mode to Vboost
          cwer idle0_f0 row1; *if flag 0 is low turn Off the boost
          cwer dcdcon_vb row2; *if vboost lower than vboost low then turn on boost
          cwer dcdcoff vb row3; *if vboost higher than vboost high then turn off boost

dcdcon:   load Vboost_H dac4h4n_ofs; *set Vboost high
          stdcctl async; *set dc dc to async
          wait row13;

dcdcoff:  load Vboost_L dac4h4n_ofs; *set Vboost low
          stdcctl sync; *set dc dc to sync
          wait row12;

idle0:    stdcctl sync;
          jocr idle0_f0;
          jmpr dcdcoff;
```

Application Source Code

```
* ### End of Channel 2 - uCore0 code
#####

* ### Channel 2 - uCore1 drives fuel pump ###

* ### Variables declaration ###
* Note: The data are stored into the dataRAM of the channel 1.
#define Ipeak 5;          ** The peak current value is stored in the Data RAM address 5
#define Ihold 6;         * * The hold current value is stored in the Data RAM address 6
#define Thold_off 7;    * * The hold off time is stored in the Data RAM address 7
#define Thold_tot 8;   ** The hold phase duration is stored in the Data RAM address 8

* Note: The Tpeak_tot variable defines the current profile time out. The active STARTx pin is expected to toggle in is
low state before this time out.

* ### Initialization phase ###

init1: stgn gain19.4 ossc;          * Set the gain of the opamp of the current measure block 1
      ldjr1 eoact1;                * Load the eoinj line label Code RAM address into the register jr1
      ldjr2 idle1;                 * Load the idle line label Code RAM address into the register jr2
      cwef jr1 _start row1;        * If the start signal goes low, go to eoinj phase

* ### Idle phase- the uPC loops here until start signal is present ###

idle1: joslr act5_start start5;    * Perform an actuation on act5 if start 5 (only) is active
      joslr act6_start start6;    * Perform an actuation on act6 if start 6 (only) is active
      jmpf jr1;                    * If more than 1 start active at the same time(or none), no actuation

* ### Shortcuts definition per the injector to be actuated ###
act5_start: dfsct hs5 ls5 undef;   * Set the 2 shortcuts: VBAT, LS
          jmpr peak1;              * Jump to launch phase
act6_start: dfsct hs5 ls6 undef;   * Set the 2 shortcuts: VBAT, LS
          jmpr peak1;              * Jump to launch phase

* ### Launch peak phase on bat ###
peak1: load Ipeak dac_osscc _ofs;  * Load the boost phase current threshold in the current DAC
      cwer hold1 cur3 row2;        * Jump to peak phase when current is over threshold
      stos on on keep;             * Turn VBAT off, BOOST on, LS on
      wait row12;                  * Wait for one of the previously defined conditions

* ### Hold phase on Vbat ###
hold1: ldcd rst _ofs keep keep Thold_tot c1; * Load the length of the total hold phase in counter 2
      load Ihold dac_osscc _ofs;    * Load the hold current threshold in the DAC
      cwer eoact1 tc1 row2;         * Jump to eoinj phase when tc1 reaches end of count
      cwer hold_on1 tc2 row3;       * Jump to hold_on when tc2 reaches end of count
      cwer hold_off1 cur3 row4;     * Jump to hold_off when current is over threshold

hold_on1:stos on on keep;          * Turn VBAT on, LS on
      wait row124;                  * Wait for one of the previously defined conditions

hold_off1:ldcd rst _ofs off on Thold_off c2; * Load the length of the hold_off phase in counter 1 and turn VBAT off,
LS on
      wait row123;                  * Wait for one of the previously defined conditions

* ### End of injection phase ###
eoact1:stos off off keep;         * Turn VBAT off, LS off
      jmpf jr2;                      * Jump back to idle phase

* ### End of Channel 2 - uCore1 code ###
```

References

8 References

Following are URLs where you can obtain information on NXP products and application solutions:

Document Number and Description		URL
MC33816	Data Sheet	www.nxp.com/files/analog/doc/data_sheet/MC33816.pdf
KIT33816FRDMUG	Kit User Guide	www.nxp.com/files/analog/doc/user_guide/KT33816UG.pdf
KITUSBSPIDGLEVME	Evaluation Kit	www.nxp.com/products/power-management/linear-regulator/evaluation-kit-usb-spi-interface-mc68hc908jw32-dongle:KITUSBSPIDGLEVME
AN4849	Application Note	www.nxp.com/files/analog/doc/app_note/AN4849.pdf
AN4954SW	SPI config file	www.nxp.com/files/analog/doc/app_note/AN4954SW.zip
nxp.com Support Pages		URL
nxp.com		www.nxp.com
MC33816 Product Summary Page		www.nxp.com/products/power-management/engine-and-dc-motor-control/powertrain-engine-control/sd6-programmable-driver-for-solenoid-control:MC33816
Analog Home Page		www.nxp.com/analog

Revision History

9 Revision History

Revision	Date	Description
1.0	6/2014	<ul style="list-style-type: none">Initial release
2.0	11/2014	<ul style="list-style-type: none">Replaced KIT33816AEEVM by KIT33816FRDMEVMUpdated References Table
3.0	2/2016	<ul style="list-style-type: none">Updated Filter Time values in Section 6.3.1.1, Filter Time, page 26Updated Filter Time values in Section 6.3.2.1, Filter Time, page 27



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Document Number: AN4954
Rev. 3.0
2/2016

